3.5X2.8mm SURFACE MOUNT SMD CHIP LED







# **Features**

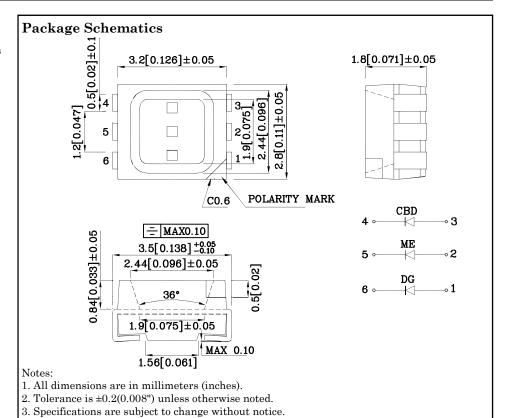
- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- $\bullet$  MSL (Moisture Sensitivity Level): 3
- RoHS compliant







# ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Absolute Maximum Ratings (T <sub>A</sub> =25°C)		DG (InGa N)	ME (AlGaIn P)	CBD (InGa N)	Unit
Reverse Voltage	$V_{\rm R}$	5	5	5	V
Forward Current	$I_{\mathrm{F}}$	30	50	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\mathrm{FS}}$	150	195	150	mA
Power Dissipation	$P_{D}$	123	125	120	mW
Electrostatic Discharge Threshold (HBM)		450	-	250	V
Operating Temperature	$T_{\rm A}$	-40 ~ +85			°C
Storage Temperature	Tstg				

Operating Characteristics (T <sub>A</sub> =25°C)	DG (InGa N)	ME (AlGaIn P)	CBD (InGa N)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	3.3	2	3.3	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	4.1	2.5	4	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	50	10	50	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λΡ	515*	632*	460*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λD	525*	624*	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$\triangle \lambda$	30	20	25	nm
Capacitance (Typ.) $(V_F=0V, f=1MHz)$	С	45	25	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	CIE127-2007* (I <sub>F</sub> =20mA) mcd		Wavelength CIE127-2007* λP nm	Angle 20 1/2
				min.	typ.		
	Green	InGaN	_	400*	577*	515*	
XZDGMECBD45S-B	Red	AlGaInP	Water Clear	80*	178*	632*	130°
	Blue	InGaN	_	80*	128*	460*	

<sup>\*</sup>Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Mar 06,2014

XDSB7053 V3-Z Layout: Maggie L.

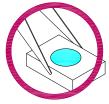


# **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

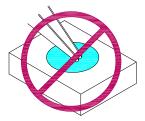
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

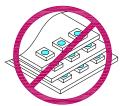


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

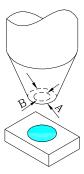




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



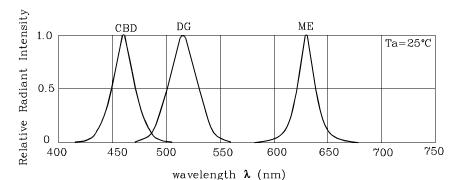
5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

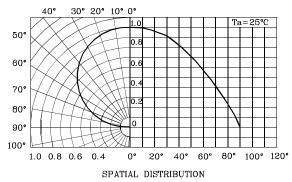






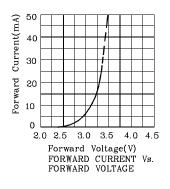


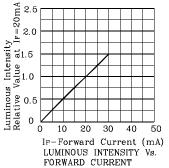


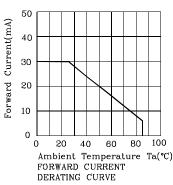


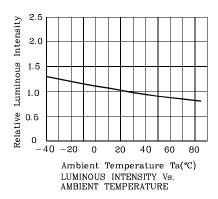
RELATIVE INTENSITY Vs. CIE WAVELENGTH

# **❖** DG

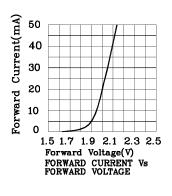


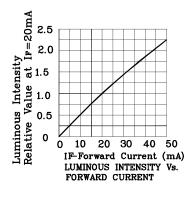


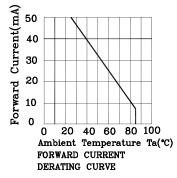


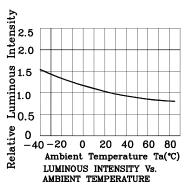


# **♦** ME

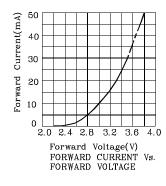


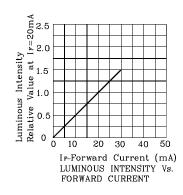


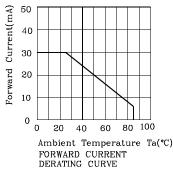


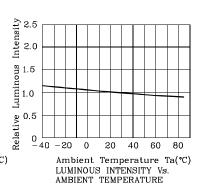


# **❖** CBD







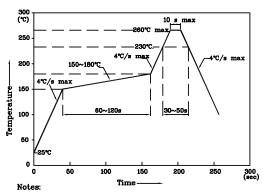






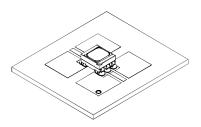
# LED is recommended for reflow soldering and soldering profile is shown below.

# Reflow Soldering Profile for SMD Products (Pb-Free Components)

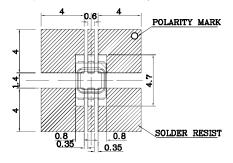


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

# ❖ The device has a single mounting surface. The device must be mounted according to the specifications.



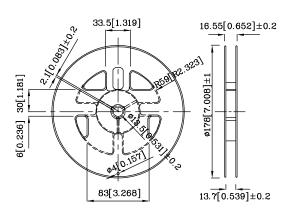
# **♦** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



# **❖** Tape Specification (Units:mm)

# TAPE 4.0±0.1 2±0.1 4.0±0.1 0.25±0.1 2.15±0.1 3 2 1 4 5 6

# Reel Dimension



## Remarks:

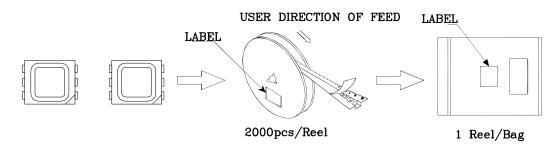
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

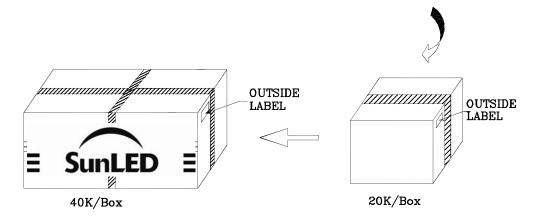
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

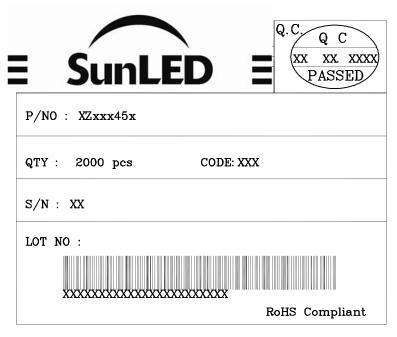
Note: Accuracy may depend on the sorting parameters.



# PACKING & LABEL SPECIFICATIONS







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